



9. IMPEDENCE CONTROL:
50 OHMS SINGLE ENDED FOR 8.5 MIL LINES ON OUTER LAYERS.
70 OHMS SINGLE ENDED FOR 4 MIL LINES ON OUTER LAYERS.
60 OHMS SINGLE ENDED FOR 5 MIL LINES ON INTERNAL LAYERS.
90 OHMS DIFFERENTIAL 4.5 MIL LINES 9.5 MIL SPACE ON ALL LAYERS.
100 OHMS DIFFERENTIAL 5.1 MIL LINES 4.9 MIL SPACE ON INTERNAL LAYERS.
8. SURFACE FINISH SHALL BE IMMERSION GOLD.
7. FINISHED BOARD SHALL BE FREE OF BURRS ON EDGES.
6. DRC'S MUST BE RUN ON THE GERBER'S BEFORE BUILDING BOARDS UNLESS PRIOR APPROVAL IS GIVEN IN WRITING.
5. PLATED THRU HOLE SIZE TOLERANCES SHALL BE +/- .003 INCH.
UNPLATED THRU HOLE SIZE TOLERANCES SHALL BE +/- .002 INCH.
4. SOLDERMASK ON BOTH SIDES OF THE BOARD SHALL BE S.M.O.B.C., LPI, COLOR GREEN.
3. MINIMUM TRACE AND SPACE SHALL BE .003 OF AN INCH.
2. COPPER PLATED SURFACE CONDUCTORS SHALL BE THE EQUIVALENT OF 1 OZ. COPPER AFTER PLATING. ALL LAYERS SHALL BE 1/2 OZ. COPPER.
1. TOTAL BOARD THICKNESS SHALL BE .062 +/- .007 INCHES.
ALL MATERIAL SHALL BE NEMA GRADE FR-4 OR EQUIVALENT. (Tg>=170 DEG. C)

NOTES: UNLESS OTHERWISE SPECIFIED

DRILL CHART			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
*	10.0	PLATED	1967
*	12.0	PLATED	198
*	20.0	PLATED	4
*	35.0	PLATED	8
*	39.0	PLATED	4
*	40.0	PLATED	40
*	47.0	PLATED	2
*	67.0	PLATED	8
*	102.0	PLATED	12
k	125.0	PLATED	4
o	35.0	NON-PLATED	2
o	40.0	NON-PLATED	2
o	43.0	NON-PLATED	1
o	47.0	NON-PLATED	4
o	53.0	NON-PLATED	13
o	63.0	NON-PLATED	13
o	80.0	NON-PLATED	32
o	100.0	NON-PLATED	32

LAYER SCHEDULE	
SCALE:	NONE
TSLK	TSLK
SMC	SMC
LAYER 1	LAYER 1
LAYER 2	LAYER 2
LAYER 3	LAYER 3
LAYER 4	LAYER 4
LAYER 5	LAYER 5
LAYER 6	LAYER 6
SMS	SMS
BSLK	BSLK

DATE	5-28-13	APPROVED		SPECTRUM DIGITAL FABRICATION DRAWING: JAMR3 APPLICATION BOARD SHEET 1 OF 1 517181 REV B	
DESIGN ENGR		CHECKED			
PROJECT ENGR		DRAFTING			
ENGR MGR		ENGR			
NEXT ASSEMBLY		DO NOT SCALE DRAWING			

1 2 3 4 5 6 7 8 9 10 11

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